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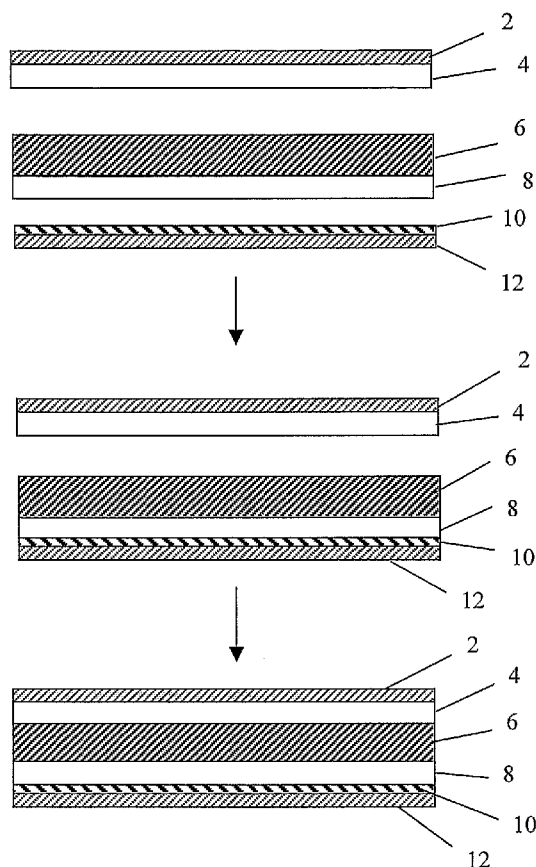
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(54) Title: METHOD OF MAKING MULTILAYERED CONSTRUCTION FOR USE IN RESISTORS AND CAPACITORS



(57) Abstract: The invention concerns a method of making multilayered constructions useful in forming capacitors and resistors, which may be used in the manufacture of printed circuit boards and microelectronic devices. According to the inventive method, a thermosetting polymer layer or layers are attached directly onto a heat resistant film layer, specifically on the side(s) of the heat resistant film to be attached to an electrically conductive layer having an electrical resistance material layer thereon. Attaching the adhesive to the heat resistant film rather than the electrically conductive layer streamlines the manufacturing process, particularly in the formation of the electrical resistance material layer onto the electrically conductive layer. This also results in better precision and uniformity of the multilayered construction.

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